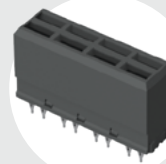




HPTS-3-S-D-VT

HPTS-6-S-D-VT



HPTS-4-S-D-VT

## HPTS SERIES

(3.20 mm) .126"

# XCede<sup>®</sup> HD POWER MODULE

### SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?HPTS](http://www.samtec.com?HPTS)

**Insulator Material:**  
Liquid Crystal Polymer  
**Contact Material:**  
Copper Alloy

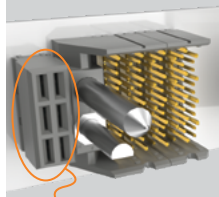
**Plating:**  
Sn or Au over  
50 μ" (1.27 μm) Ni  
**Operating Temp Range:**  
Testing Now!

**Current Rating:**  
Testing Now!  
**RoHS Compliant:**  
Yes

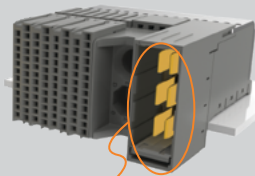
**Mates with:**  
BSP  
(See HDTF for more information)

Mounts individually to backplane

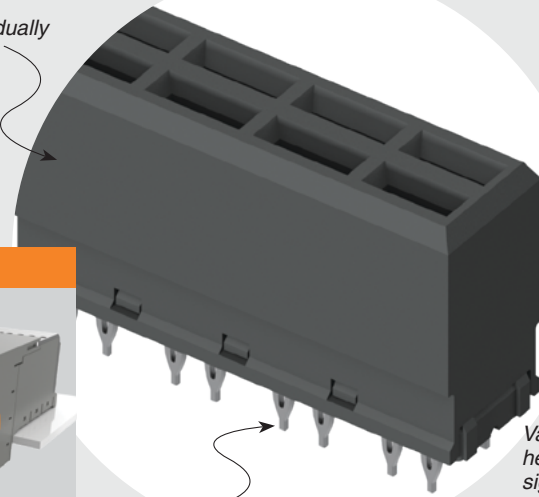
### APPLICATION



HPTS Series individually mounts to backplane



Mates with integrated receptacle (BSP Series) configured with power module



Press-fit tails

Variety of body heights to match signal module pair count

### TOOLING

- For press-fit extraction and insertion tool options, visit [www.samtec.com/tooling](http://www.samtec.com/tooling)

### HPTS

### BODY HEIGHT

### PLATING

### D

### ORIENTATION

(Based on pair count of signal modules (HDTF Series))

**-3**

= For use with 3 pair HDTF Series

**-4**

= For use with 4 pair HDTF Series

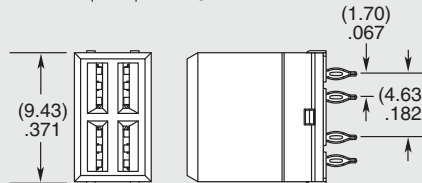
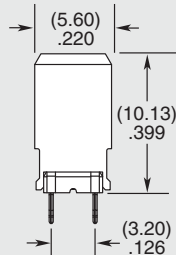
**-6**

= For use with 6 pair HDTF Series

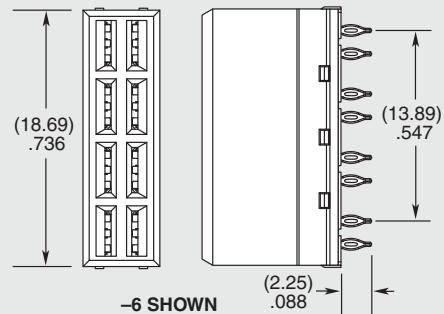
**-S**

= 30 μ" (0.76 μm)  
Gold in contact area,  
Matte Tin on tail

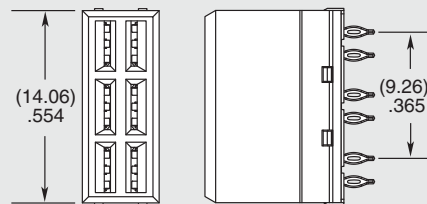
**-VT**  
= Vertical



-3 SHOWN



-6 SHOWN



-4 SHOWN

**Note:**  
XCede<sup>®</sup> is a registered trademark of Amphenol.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications.  
Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.